

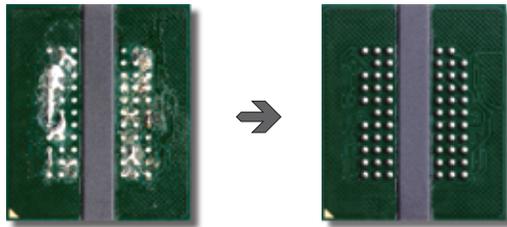


### BGA Component Re-Balling Service

Given the rapid shift of semiconductor products being manufactured in BGA packages, **POLYSTAK** now offers customers an important service of re-balling BGA components. Our global facilities are equipped to provide a cost effective, quick turn service and 100% electrical testing to eliminate discarding expensive electrically good BGA devices that require re-balling.

#### Definition of Service

Replace damaged solder balls on BGA package in order to make it fully functional and like-new condition.



#### Scope of Service

- Detach defective BGA package from board
- Desolder pad area in module
- Remove damaged solder balls from BGA packaged device and mount new solder balls
- Cleaning before/after re-balling process
- Test repaired BGA packaged device (optional)
- Mount repaired device on module (optional)
- Test on the module level (optional)
- Inspection

#### Re-balling Production Flow

